



捷飞高电路电子有限公司
JETFGO Circuits Limited

专业生产印制 电路板厂家

PROFESSIONAL PCB
MANUFACTURER

www.jiefeigao.com

COMPANY PROFILE

公司简介

捷飞高电路电子有限公司成立于 2004 年，位于深圳市宝安区福永镇，是一家专业生产样板、中大批量厂家。经过 17 年的发展，公司拥有一支经验丰富的管理团队和强大的工程研发队伍，公司配置先进的生产设备，拥有高超的技术能力以及完善的质量管理体系。公司已通过美国 UL 认证 (UL 档案号 :E218213)、ISO9001:2015、ISO14001:2015X CQCOATF16949-2016 认证。

工厂以样板制造为基础，向中小批量延伸，实现适度的经营规模。以技术进步引领企业发展，满足客户提出的制造高档产品和特殊产品的要求。紧跟行业技术发展步伐，在特色技术领域寻找发展，快速响应市场要求，快速准时交付产品。

公司产品广泛应用于通讯、工业控制、计算机、军工、医疗、航空、汽车、消费类等领域。随着 PCB 精细化的要求，公司大力发展多层板、HDI 板。逐步形成以多层板、HDI 板、高频板为主导的格局。样板可以做到 54 层，每月产能 20000 平方米。

JETFGO Circuits Limited, established in 2004, is located in Fuyong Town, Bao'an District, Shenzhen. It is a professional manufacturer of model and small and medium, mass production batch. After 17 years of development, the company has an experienced management team and a strong engineering R & D team. The company is equipped with advanced production equipment, superb technical ability and perfect quality management system. The company has passed UL certification (UL file No.: e218213), ISO9001:2015, ISO14001:2015X CQCOATF16949-2016. Based on model manufacturing, the factory extends to small and medium-sized batches to achieve an appropriate business scale. Lead the development of the enterprise with technological progress and meet the requirements of customers for manufacturing high-end products and special products. Keep up with the pace of industrial technology development, seek development in the field of characteristic technology, quickly respond to market requirements and deliver products on time. The company's products are widely used in communication, industrial control, computer, military industry, medical treatment, aviation, automobile, consumer and other fields. With the requirements of PCB refinement, the company vigorously develops multilayer board and HDI board. Gradually form a pattern dominated by multi-layer board, HDI board and high-frequency board. The model can achieve 54 floors, with a monthly production capacity of 20000 square meters.



COUPORATE CULTURE

企业文化



愿景 /VISION

将捷飞高电路打造成国内外高端印制板行业的品牌企业

We are deeply committed to remain JFG toward top PCB brand enterprise both at home and abroad.



使命 /MISSION

为中国芯的不断进步，贡献我们的力量。

We must actively contribute to the continuously improving of Chinese Core.



经营理念 /PHILOSOPHY

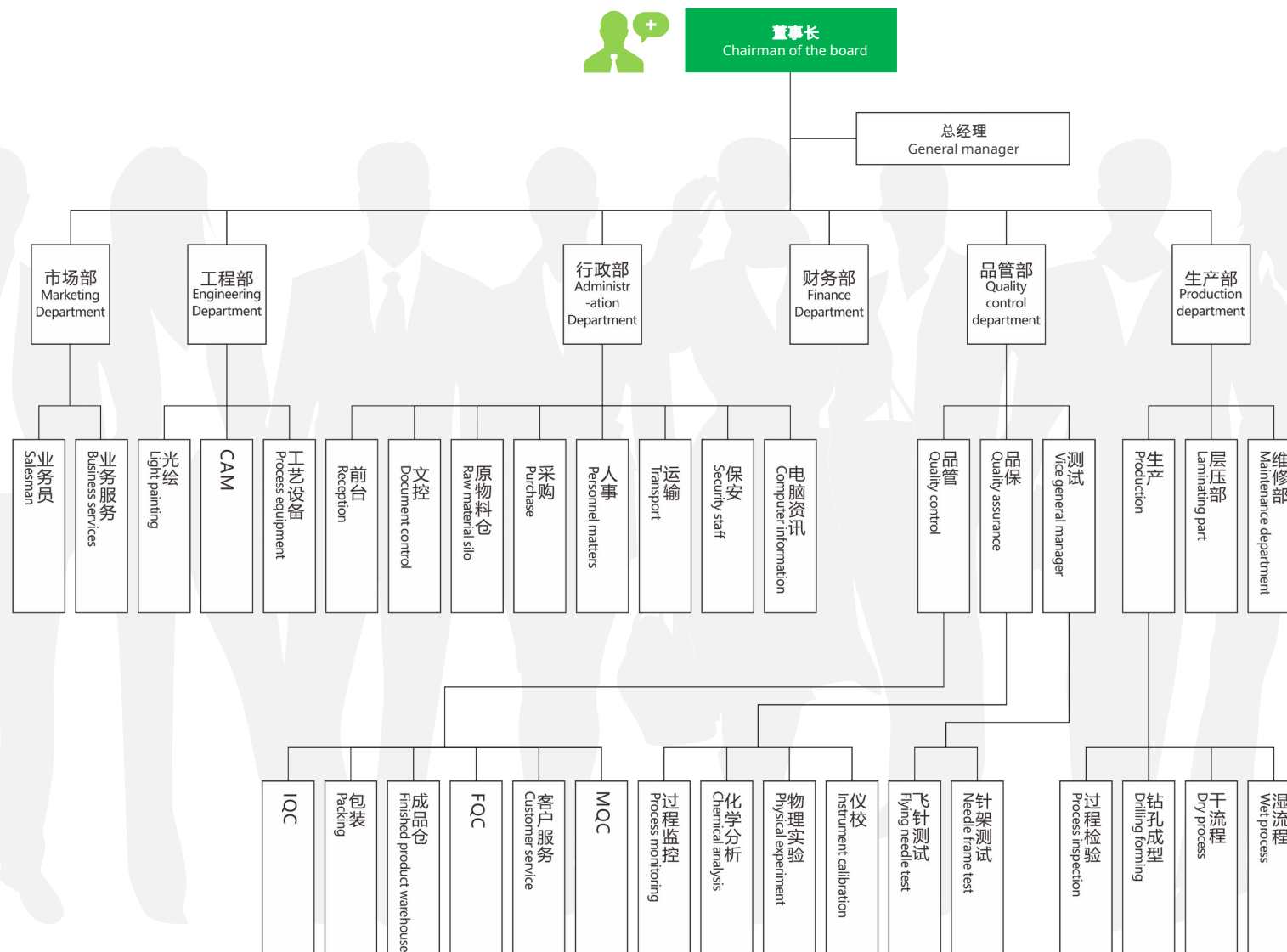
开拓创新、持续改进、追求卓越

We must actively contribute to the continuously improving of Chinese Core.



ORGANIZATIONAL STRUCTURE

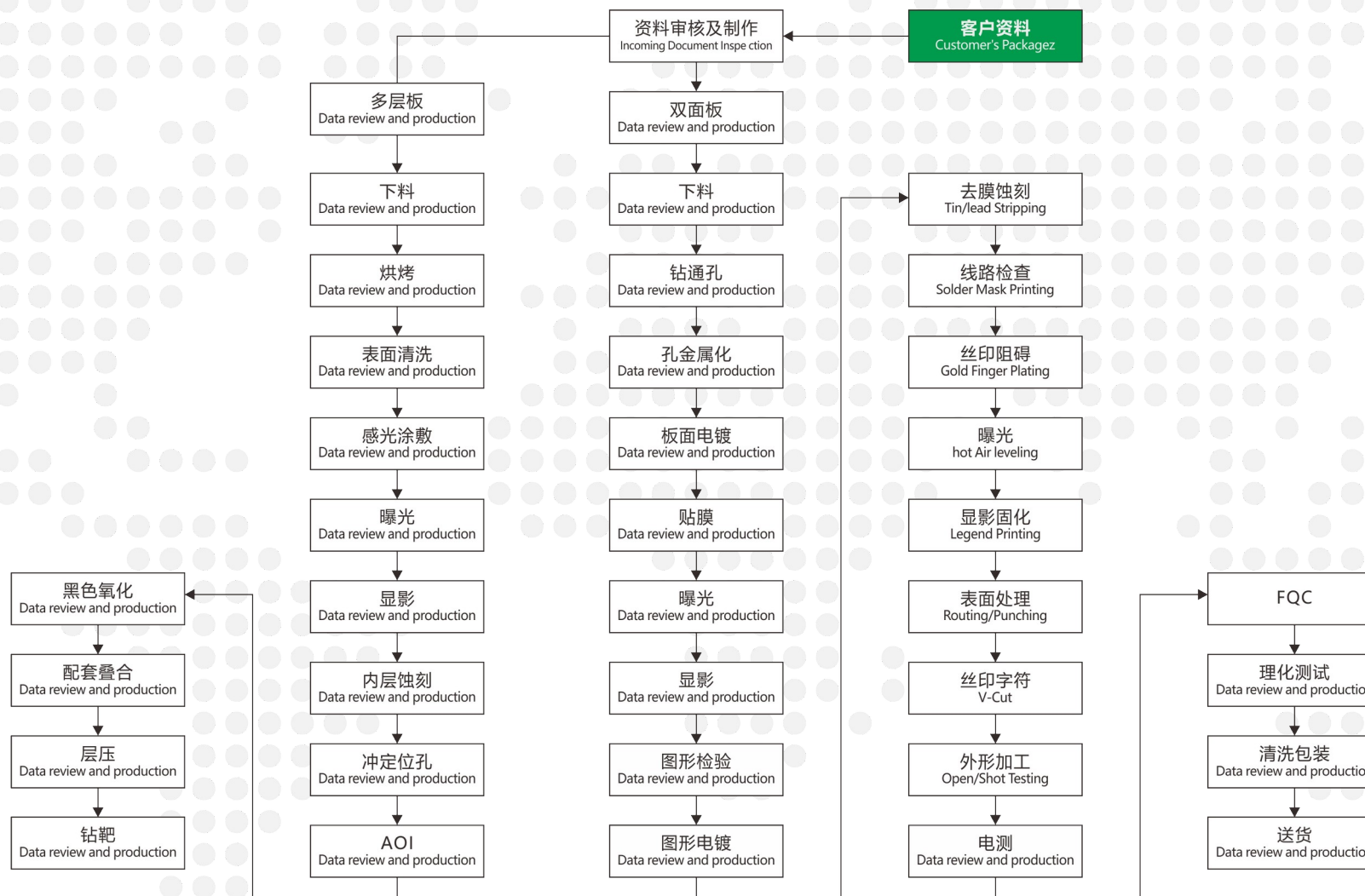
组织架构





PROCESS FLOW

工艺流程





PROCESS CAPABILITY

工艺能力

可生产层数 Number of producible layers	2-54层 (L)
最大加工尺寸 Maximum machining size	600mm*1200mm
可生产板厚度 Producible plate thickness	0.2mm-6.5mm
可生产铜厚 Can produce thick copper	0.5OZ-28OZ
最小线宽/线距 Minimum line width line spacing	2.0-3.5mil

最小成品孔径 Minimum finished aperture	0.10mm
最大厚径比 Maximum thickness diameter ratio	15:1
过孔处理 Via treatment	通孔、盲孔、埋孔、沉孔、盘中孔 Through hole, blind hole, buried hole, counterbore, pan hole
表面处理 surface treatment	化学沉金、镀金、化学沉锡、化学沉银、防氧化、喷锡 Chemical gold precipitation, gold plating, chemical tin precipitation, chemical silver precipitation, anti-oxidation and tin spraying
常用板材 Common plate	FR4、HTC、无卤素、金属基板、高频材料 FR4, HTC, halogen free, metal substrate, high frequency material

PRODUCT DELIVERY DATE

产品交期

专业生产印制电路板厂家
PROFESSIONAL
PCB MANUFACTURER

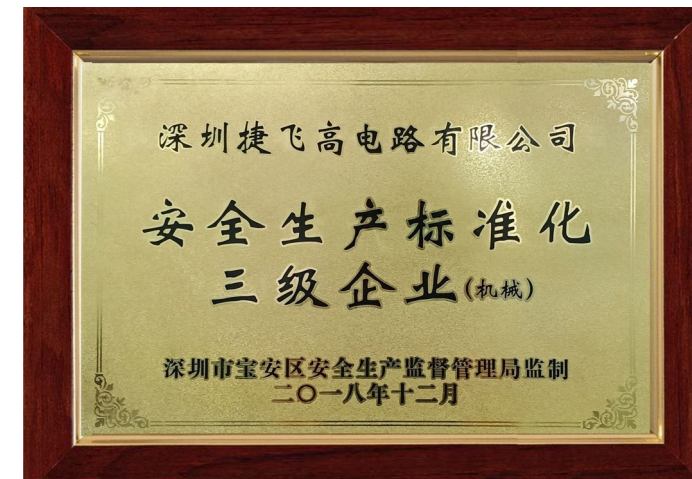
样板加工时间 Sample processing time		
类型 Type	最快交期 Fastest delivery date	正常交期 Normal delivery date
双面板Double sided board	24小时(hour)	3天(Day)
4层板Laminate	36小时(hour)	5天(Day)
6层板Laminate	48小时(hour)	6天(Day)
8层板Laminate	72小时(hour)	7天(Day)
10层板Laminate	4天(Day)	9天(Day)
12层板Laminate	4天(Day)	11天(Day)
14层板Laminate	5天(Day)	13天(Day)
16层板Laminate	5天(Day)	15天(Day)
18层板Laminate	7天(Day)	15天(Day)
20层板及以上Ply and above	待协商To be negotiated	待协商To be negotiated

批量加工时间 Batch processing time	
类型 Type	交期 Delivery date
双面板Double sided board	7天(Day)
4层板Laminate	10天(Day)
6层板Laminate	12天(Day)
8层板Laminate	12天(Day)
10层板Laminate	14天(Day)
12层板Laminate	16天(Day)
14层板Laminate	16天(Day)
16层板Laminate	18天(Day)
18层板Laminate	18天(Day)
20层板及以上Ply and above	待协商To be negotiated

QUALIFICATION CERTIFICATE

资质证书

- ① 一次合格率：> 95% ② 交货准确率：> 98% ③ 客户投诉率：< 1%
- First pass rate: > 95% Delivery accuracy: > 98% Customer complaints: < 1%



QUALIFICATION CERTIFICATE

资质证书



QUALITY ASSURANCE

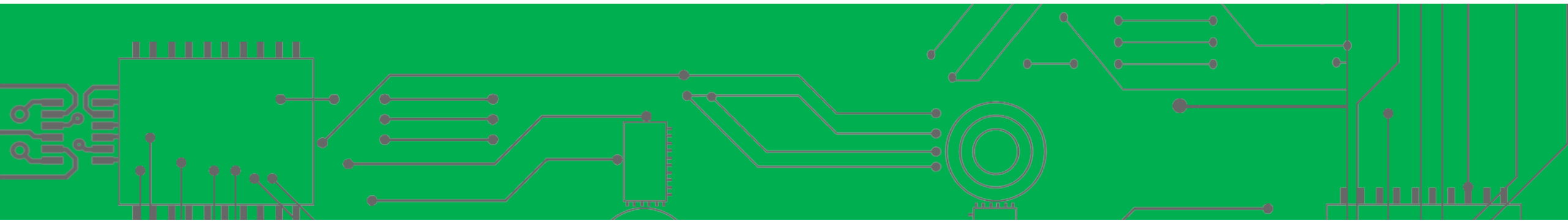
质量管理

- ◆ Metallographic microsection
- ◆ Thermal stress testing
- ◆ Ionic contamination test
- ◆ Anti-peel/tensile test

- Bridge test
- ◆ Impedance Control test
 - ◆ Withstand voltage test
 - ◆ Insulation test

- ◆ X-RAY thickness measurement
- ◆ ROHS testing
- ◆ Salt spray test

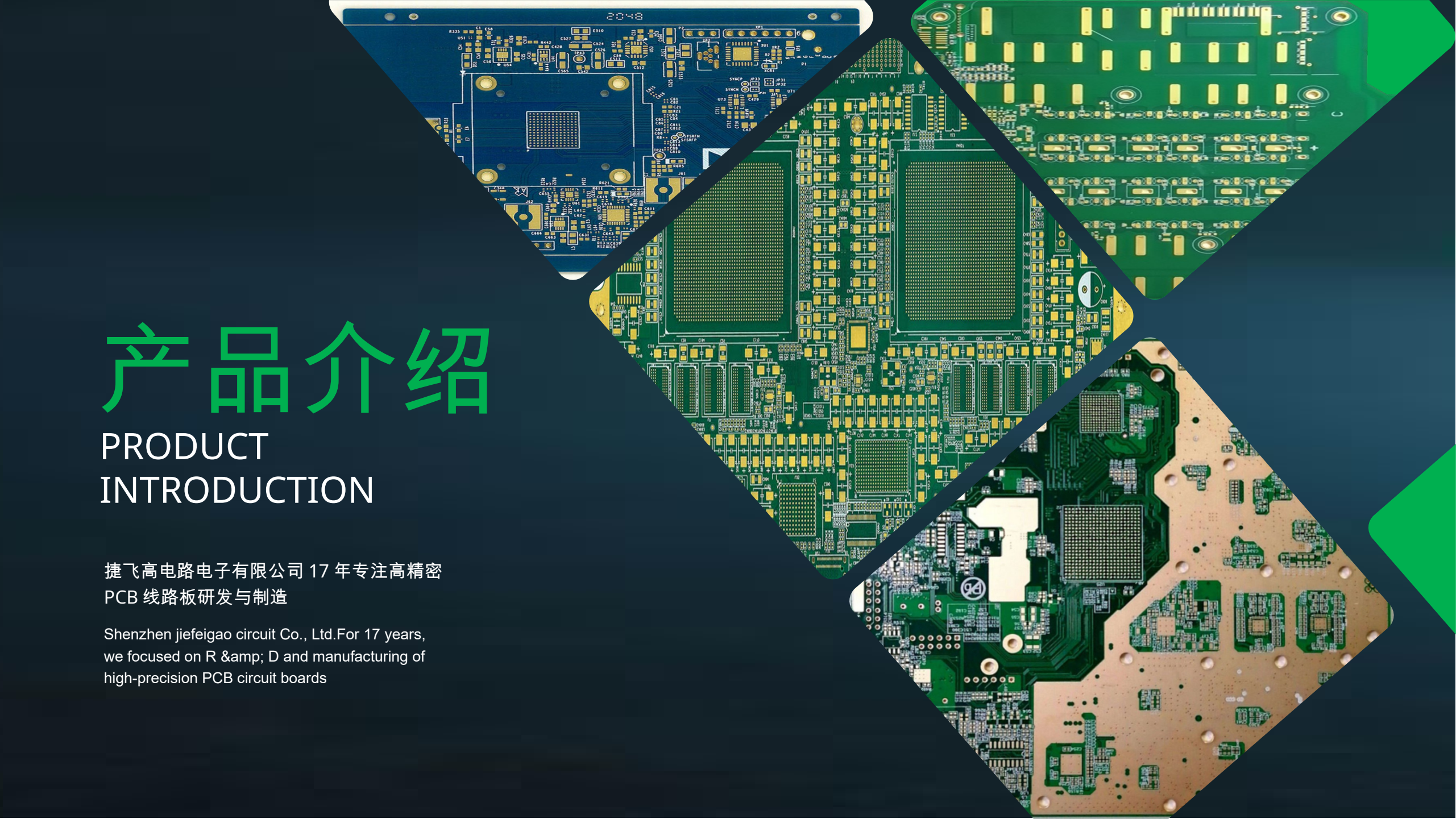
- ◆ Constant temperature and humidity test
- ◆ High and low temperature impact test
- ◆ High and low temperature cycle test



Mainly Customers Lists

主要客户





产品介绍

PRODUCT INTRODUCTION

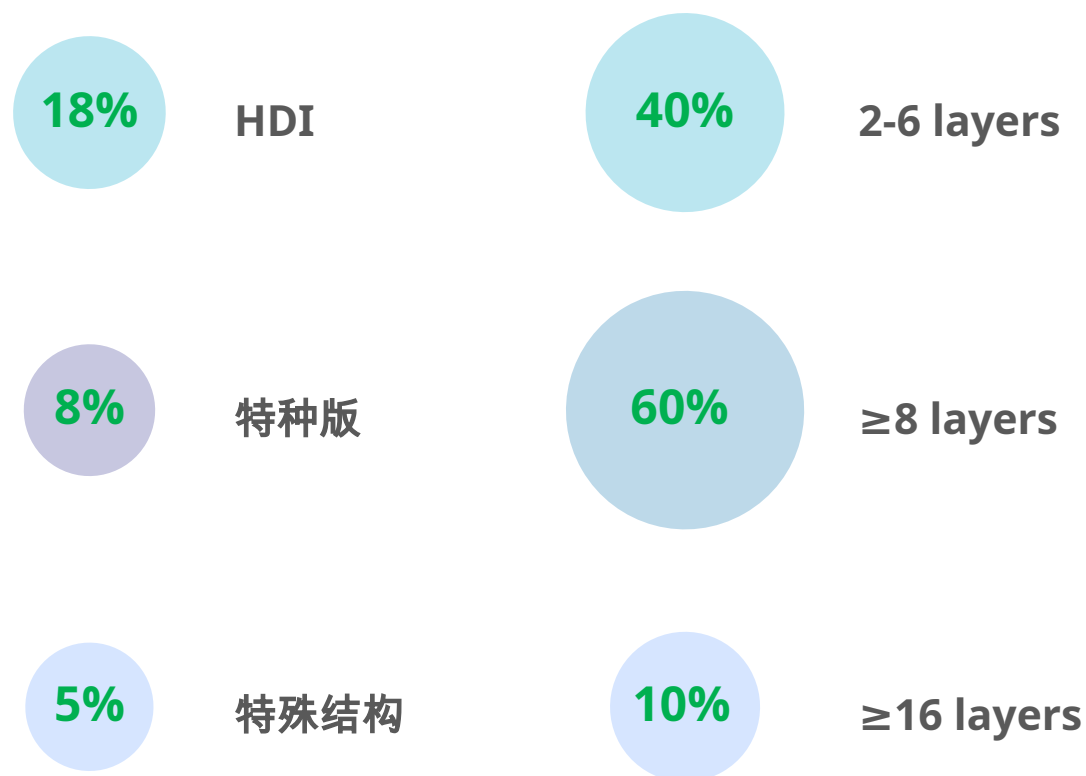
捷飞高电路电子有限公司 17 年专注高精密
PCB 线路板研发与制造

Shenzhen jifeigao circuit Co., Ltd. For 17 years,
we focused on R & D and manufacturing of
high-precision PCB circuit boards



PRODUCT

我们的产品



我们的产品 Our products

- ◆ 多层板
- ◆ 刚柔结合板
- ◆ HTG 厚铜箔板
- ◆ 高频通讯板
- ◆ 混合介质板
- ◆ 盲埋孔板
- ◆ 金属芯 (基) 板
- ◆ HDI
- ◆ multilayer board
- ◆ rigid flexible combination plate
- ◆ HTG thick copper foil
- ◆ high frequency communication board
- ◆ mixed media board
- ◆ blind buried orifice plate
- ◆ metal core (base) plate
- ◆ HDI

PRODUCT APPLICATION FIELD

部分产品应用领域



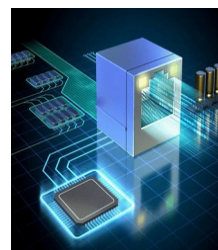
医疗
Medical care



工业电源
Industrial power supply



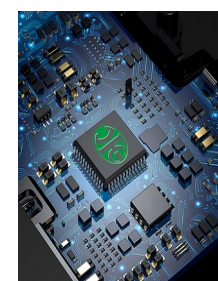
通信高速背板
Communication high speed backplane



通信高频
Communication high frequency



军工通信高频
Military communication high frequency



IC 测试板
IC test board



工业控制
Industrial control



汽车
Automobile

广泛应用于医疗、工业电源、通信高速背板、通信高频、军工通信高频、IC 测试板、工业控制、汽车等行业。

It is widely used in medical treatment, industrial power supply, communication high-speed backplane, communication high frequency, military communication high frequency, IC test board, industrial control, automobile and other industries.

六、四层板 Six 、 Four layer plate

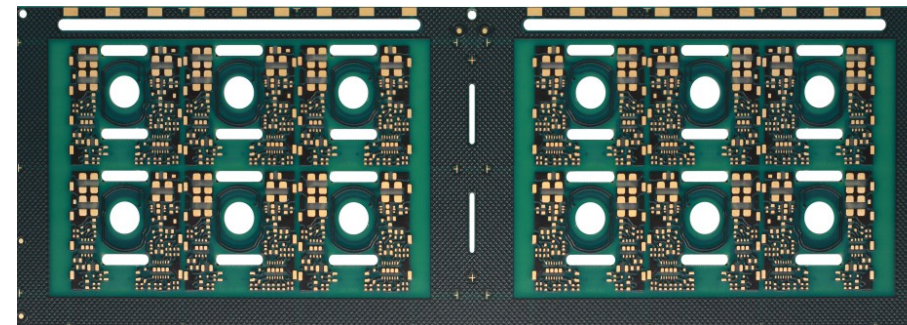


应用领域 : 医疗

APPLICATION:MEDICAL CARE

板厚 : 硬板 6 层 1.6mm 软板 4 层 0.25mm	Plate thickness: 6 layers of hard plate 1.6mm, 4 layers of soft plate 0.25mm
板材 : 松下 +S1000-2	Plate: Panasonic + s1000-2
线宽线距 : 4/4mil	Line width / line spacing: 4/4mil
最小孔 : 0.2mm	Minimum hole: 0.2mm
表面工艺 : 沉金	Surface technology: gold deposition
工艺特点 : 刚柔结合	Process features: rigid flexible combination

十二层板 Twelve layer plate



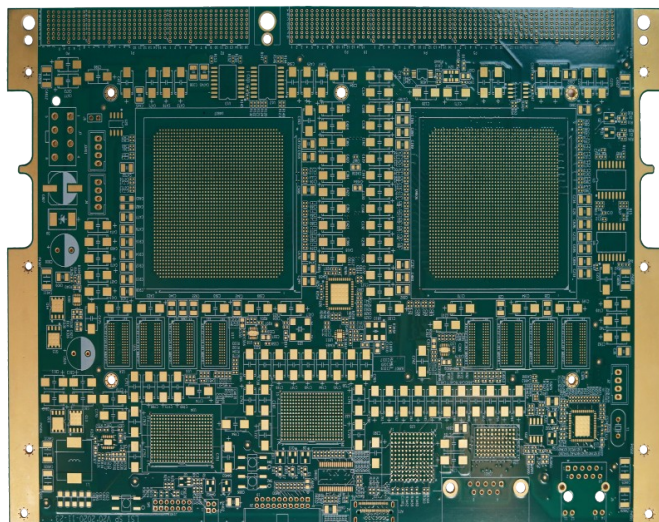
应用领域 : 工业电源

APPLICATION:INDUSTRIAL POWER SUPPLY

板厚 : 3.0mm	Plate thickness: 3.0mm
板材 : S1000-2	Plate: S1000-2
线宽线距 : 8/10mil	Line width line spacing: 8/10mil
最小孔 : 0.35mm	Minimum hole: 0.35mm
表面工艺 : 沉金	Surface technology: Sink gold
工艺特点 : 树脂塞 孔 , 内层 4OZ, 覆盖膜	Process features: resin plug hole, inner layer 4oz, covering film



二十四层板 Twelve layer plate

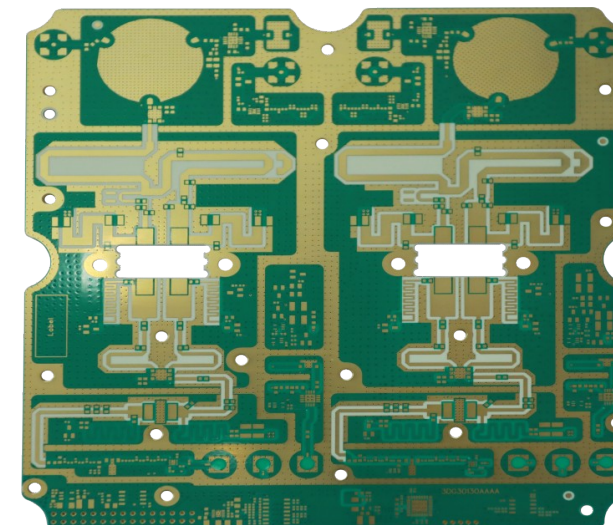


应用领域：通信高速背板

APPLICATION: COMMUNICATION HIGH SPEED BACKPLANE

板厚：3.0mm	Plate thickness: 3.0mm
板材：松下 M6	Plate: Panasonic M6
线宽线距：3.5/4mil	Line width / line spacing: 3.5/4mil
最小孔：0.25mm	Minimum hole: 0.25mm
表面工艺：沉金	Surface technology: gold deposition
工艺特点：12 组背钻, 32 组阻抗，控深阶梯，阴阳铜	Process features: 12 sets of back drilling and 32 sets of impedance. Depth control ladder, Yin Yang copper

六层板 Six layer plate



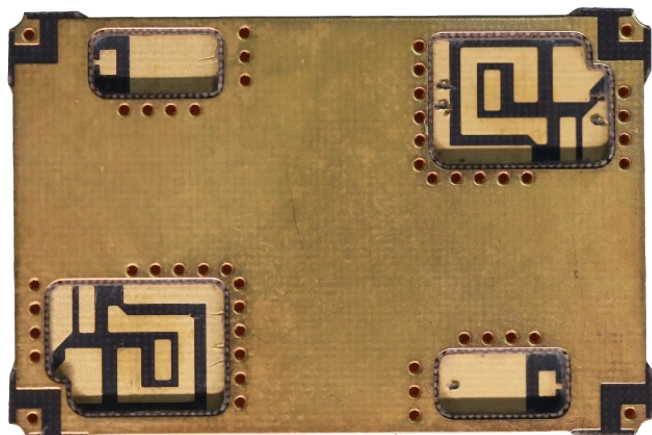
应用领域：通信高频

APPLICATION: COMMUNICATION HIGH FREQUENCY

板厚：2.4mm	Plate thickness: 2.4mm
板材：TU872+R4350 混压	Plate: TU872 + R4350 mixed pressure
线宽线距：5.9/6.0mil	Line width / line spacing: 5.9/6.0mil
最小孔：0.3mm	Minimum hole: 0.3mm
表面工艺：沉金	Surface technology: gold deposition
工艺特点：高厚径比	Process features: height thickness diameter ratio



高频三层板 High frequency three-layer board



应用领域: 军工通信高频

APPLICATION: MILITARY COMMUNICATION HIGH FREQUENCY

板厚: 3.2mm

板材: F4BME-1/2

线宽线距: +Rogers4450-PP, 12/14mil

最小孔: 0.6mm

表面工艺: 沉金

工艺特点: 台阶板, 金属包边半孔, 控深加盖

Plate thickness: 3.2mm

Plate: F4BME-1 / 2 + rogers4450 PP

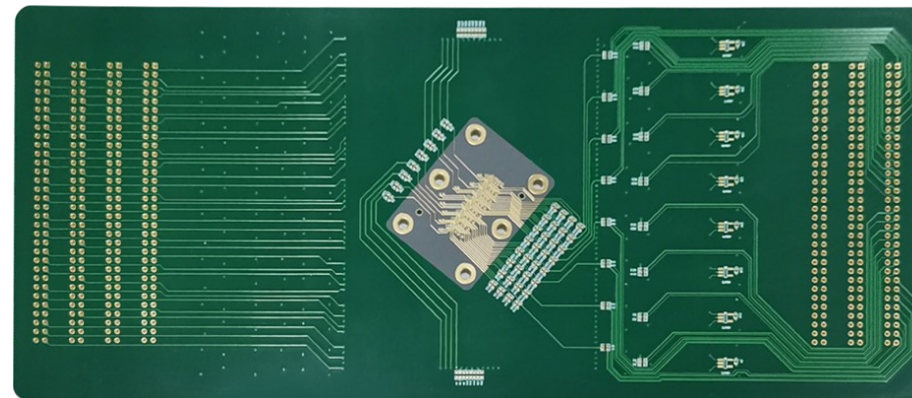
Line width / line spacing: 12 / 14mil

Minimum hole: 0.6mm

Surface technology: gold deposition

Process features: step plate, metal edging, half hole, depth control and capping

十层板 二阶 Ten layer plate second order



应用领域: IC 测试板

APPLICATION: IC TEST BOARD

板厚: 3.0mm

板材: S1000-2

线宽线距: 6/8mil

最小孔: 0.2mm

表面工艺: 镀金 30U

工艺特点: 盲孔结构, 3-8/8-10/9-10, 盘中孔, 树脂塞孔

Plate thickness: 3.0mm

Plate: S1000-2

Line width / line spacing: 6 / 8mil

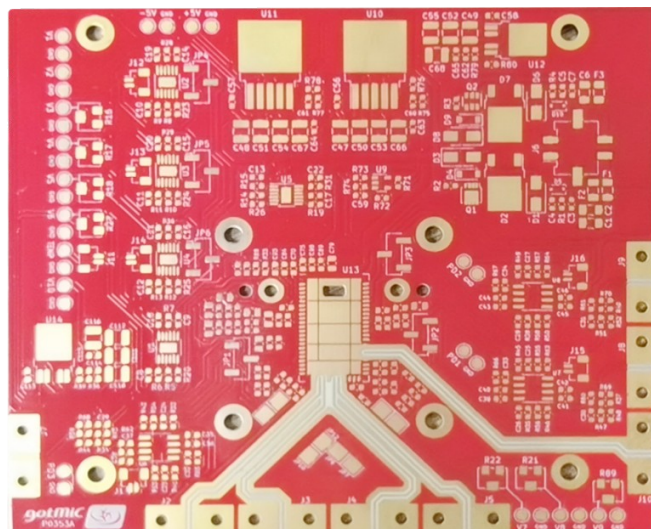
Minimum hole: 0.2mm

Surface technology: Gold Plated 30U

Process features: blind hole structure 3-8/8-10/9-10, disc hole, resin plug hole



三层板 Three layer plate



应用领域：工业控制

APPLICATION:INDUSTRIAL CONTROL

板厚：1.2mm

板材：铜基 +R4350

线宽线距：8/8mil

最小孔：0.5mm

表面工艺：沉金

工艺特点：铜基 + 罗杰斯混压

Plate thickness: 1.2mm

Plate: copper base + r4350

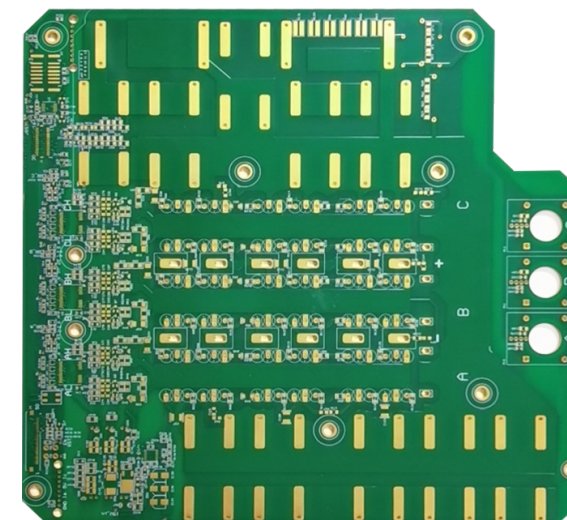
Line width / line spacing: 8 / 8mil

Minimum hole: 0.5mm

Surface technology: gold deposition

Process features: copper base + Rogers
mixed pressure

八层硬板 Eight layer hard board



应用领域：汽车

APPLICATION:AUTOMOBILE PLATE

板厚：4.5mm

板材：FR4 Tg170

线宽线距：8/9MIL

最小孔：0.4mm

表面工艺：沉金

工艺特点：全板过孔树脂塞
孔，外层 3oz，内层
4oz，IC 管脚大小一致

Plate thickness: 4.5mm

Plate: FR4 tg170

Minimum aperture: 0.4mm

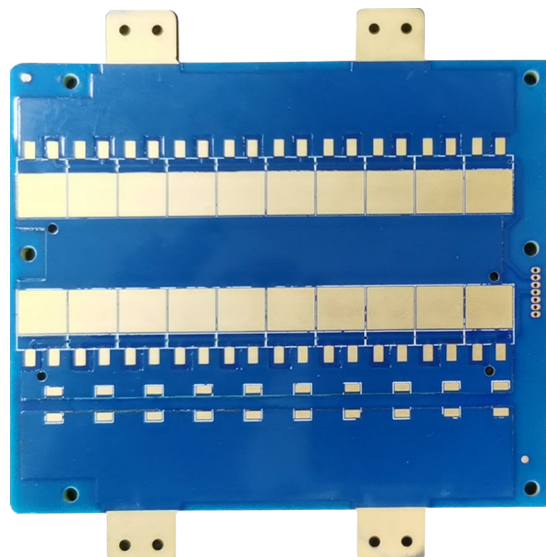
Line width and line spacing: 8 / 9MIL

Surface technology: gold deposition

Process features: full board through-hole
resin plug hole, the outer layer is 3oz, the
inner layer is 4oz, and the size of IC pins
is the same



一层板 One layer plate



应用领域 : 充电桩

APPLICATION:CHARGING PILE

板厚 : 5.0mm

板材 : 铝材、紫铜块

线宽 / 线距 : 10/8mil

最小孔径 : 0.7mm

表面工艺 : 沉金

工艺特点 : 嵌铜块

Plate thickness: 5.0mm

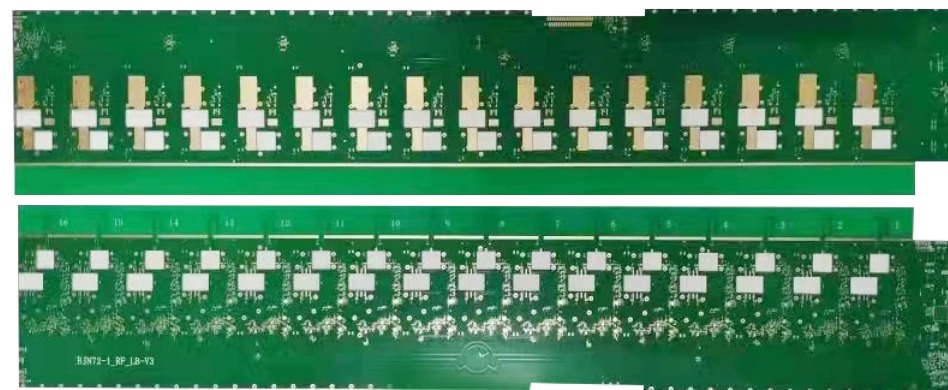
Plate: Aluminum, red copper
blockWidth/pitch: 10/8mil

Minimum aperture: 0.7 mm

Surface technology: gold deposition.

Technological features: copper block
embedded.

六层板 Six-layer board



应用领域 : 通信

APPLICATION:COMMUNICATION

板厚 : 2.0mm

板材 : PR-4 TG170

线宽线距 : 3/3mil

最小孔 : 0.2mm

表面工艺 : 沉金

工艺特点 : 1100*300 超长

Plate thickness: 2.0mm

Panel: PR-4 TG170

Line width: 3/3mil

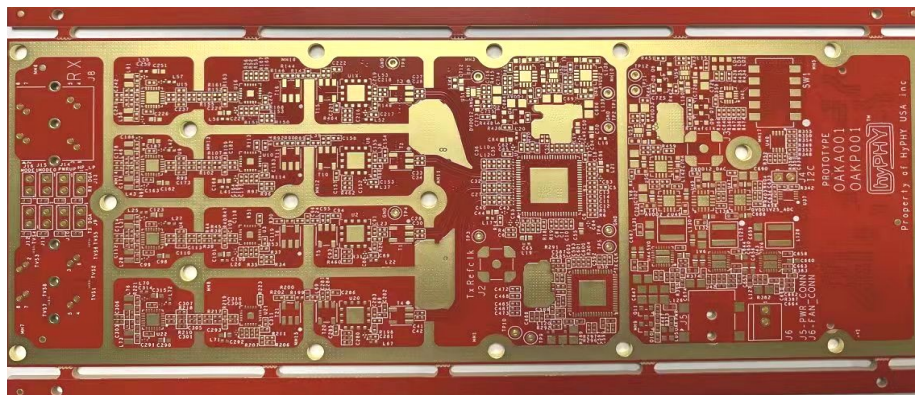
Minimum hole: 0.2mm

Surface technology: gold deposition.

Technological features: 1100*300 super
long.



十二层板 Twelve layer plate



应用领域：通信

APPLICATION:COMMUNICATION

板厚：2mm

板材：松下 M6

线宽 / 线距：4/4mil

最小孔径：0.3

表面工艺：沉金

工艺特点：1-2/1-3/1-4/9-12/10-12/11-12 六组盲孔 + 树脂塞孔 + 阻抗

Plate thickness: 2mm

Plate: Panasonic M6

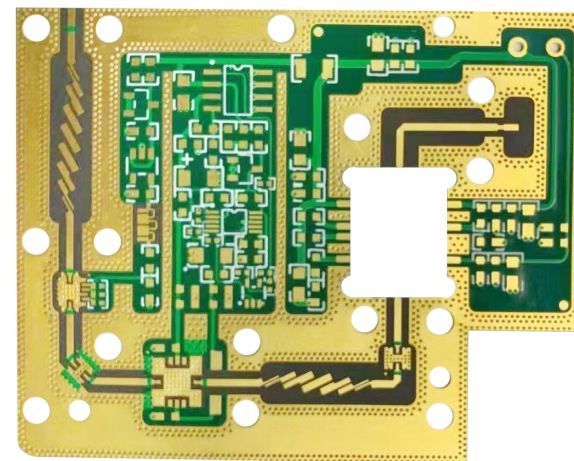
Line width / line spacing: 4 / 4mil

Minimum aperture:0.3

Surface technology: gold deposition

Process features: 1-2 / 1-3 / 1-4 / 9-12 / 10-12 / 11-12 six groups of blind holes + resin plug holes + impedance

二层 罗杰斯 Second floor Rogers



应用领域：通信

APPLICATION:COMMUNICATION

板厚：0.254mm

板材：罗杰斯 5880

线宽线距：8/10mil

最小孔：0.15mm

表面工艺：沉金

工艺特点：铜浆塞孔 线宽精度 +/-0.02MM

Plate thickness:0.254mm

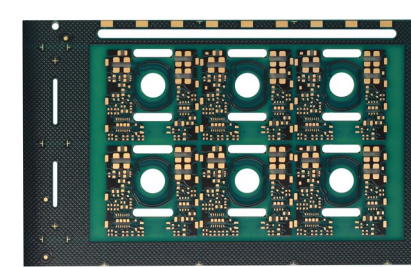
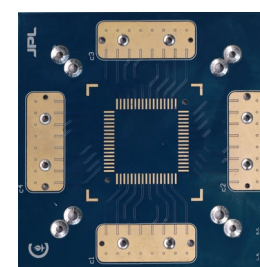
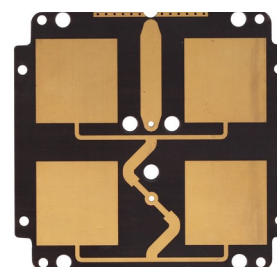
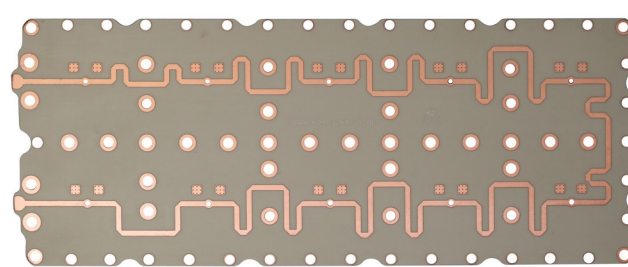
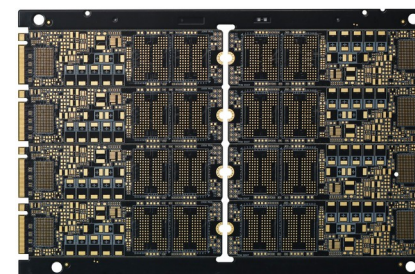
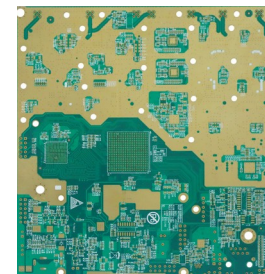
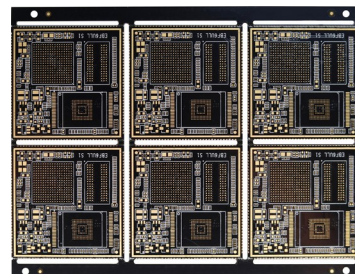
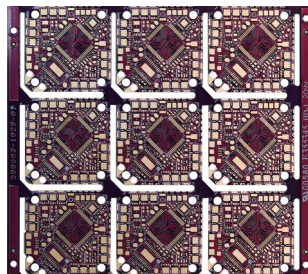
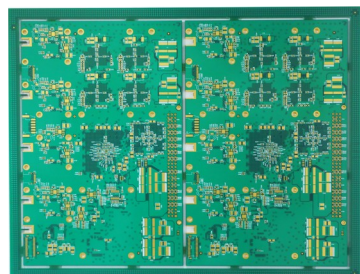
Plate: Rogers 5880.

Line width: 8/10mil.

The minimum hole: 0.15mm

Surface technology: gold deposition.

Technological features: high frequency board+copper paste plug hole



车间设备

WORKSHOP AND
EQUIPMENT



板料仓库
Sheet metal warehouse



内层车间
Inner workshop





捷飞高电路电子有限公司能为客户提供优质的
电路板生产和设计方案，将是您满意的 PCB
合作伙伴。

Shenzhen jiefeigao circuit Co., Ltd. can provide
customers with high-quality circuit board production
and design solutions, and will be your satisfactory PCB
partner.

压合机
Press machine





钻孔车间
Drilling workshop

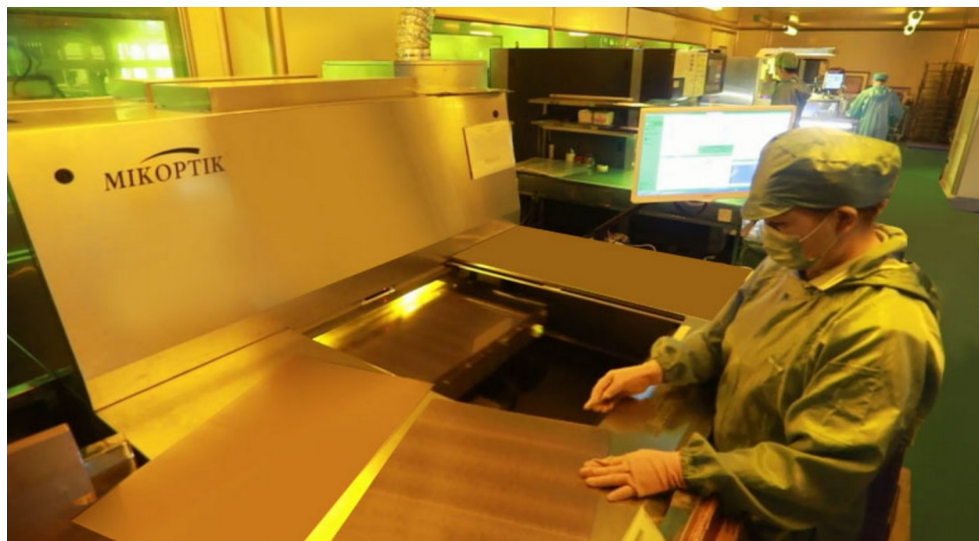
WORKSHOP EQUIPMENT

车间设备

图电自动线

Figure electric automatic line





磨板机 / 阻焊显影
Plate grinder / solder resist developer



干区车间
Dry area workshop





捷飞高电路电子有限公司
JETFGO Circuits Limited

WORKSHOP EQUIPMENT

车间设备



捷飞高电路电子有限公司能为客户提供优质的电路板生产和设计方案，将是您满意的 PCB 合作伙伴。

Shenzhen jiefeigao circuit Co., Ltd. can provide customers with high-quality circuit board production and design solutions, and will be your satisfactory PCB partner.



捷飞高电路电子有限公司
JETFGO Circuits Limited

WORKSHOP EQUIPMENT

车间设备



外形车间
Shape workshop

WORKSHOP EQUIPMENT

车间设备



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废气废水处理循环设备

Waste gas and wastewater treatment circulating equipment





WORKSHOP EQUIPMENT

车间设备

沉金电金车间
Gold deposition and electrogold workshop



THANK

感谢观看

